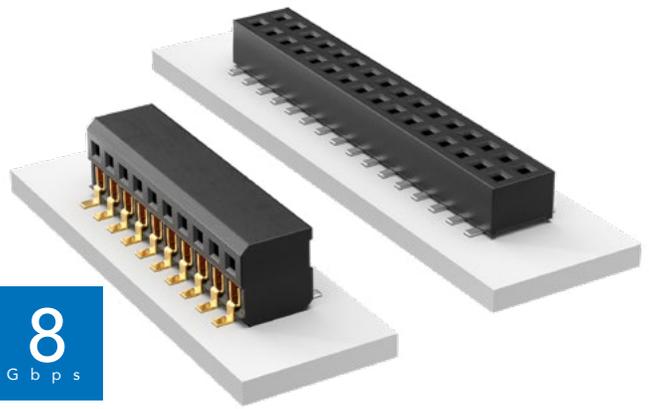




LOW-PROFILE DUAL WIPE SOCKET



(1.27 mm) .050" PITCH • A-CLP SERIES

A-CLP

Mates:

A-FTSH, A-FW



SPECIFICATIONS

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Sn or Au over
50 μm (1.27 μm) Ni

Current Rating (A-CLP/A-FTSH):

3.4 A per pin
(2 pins powered)

Voltage Rating:

280 VAC/395 VDC

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

Top Entry =
(1.40 mm) .055" minimum

Bottom Entry =
(2.41 mm) .095" minimum

plus board thickness

DH Entry =
(2.31 mm) .091" to (2.67 mm) .105"

Normal Force:

60 grams (0.59 N) average

Max Cycles:

100 with 10 μm (0.25 μm) Au

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-35)

(0.15 mm) .006" max (36-50)*

*(.004" stencil solution

may be available; contact

ipg@samtec.com)

ALSO AVAILABLE

MOQ Required

Single row

Other platings



Note:

Some lengths, styles and options are non-standard, non-returnable.



02 thru 50

-L
= 10 μm
(0.25 μm)
Gold on
contact,
Matte Tin
on tail

-S
= Single
Row
-D
= Double
Row

-DH
= Double
Horizontal
(Requires
A-FTSH-04
lead style)

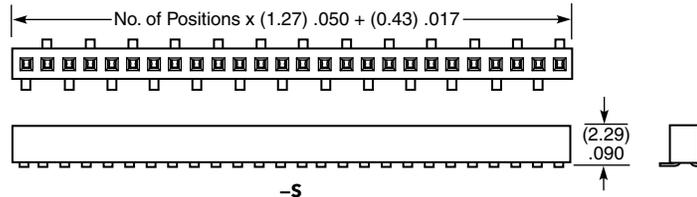
Leave blank
for single row

-BE
= Bottom Entry
(Required for
bottom
entry
applications)

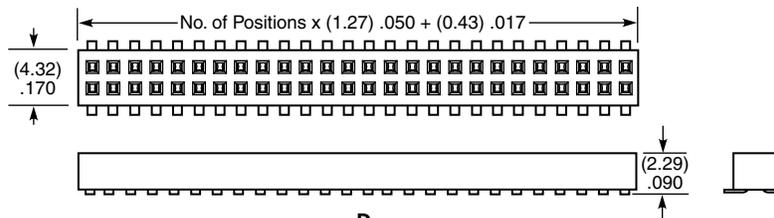
-A
= Alignment Pin
(05, 06, 07, 08,
10, 12, 15,
20, 25, 30, 40
positions only)
(-DH option and
other sizes.
Contact Samtec.)

-K
= (4.00 mm)
.157" DIA
Polyimide film
Pick & Place Pad
(3 positions
minimum)

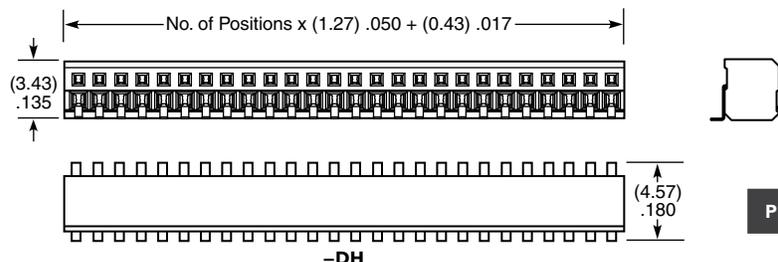
-TR
= Tape & Reel



-S

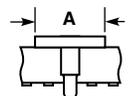


-D



-DH

PIN/ROW	A
04-15	(3.56) .140
16-50	(7.11) .280



If odd pins/row, alignment pins are on middle position on centerline of the part. If even pins/row, then alignment pins are between middle two positions.

Due to technical progress, all designs, specifications and components are subject to change without notice.